

IN THE CLAIMS:

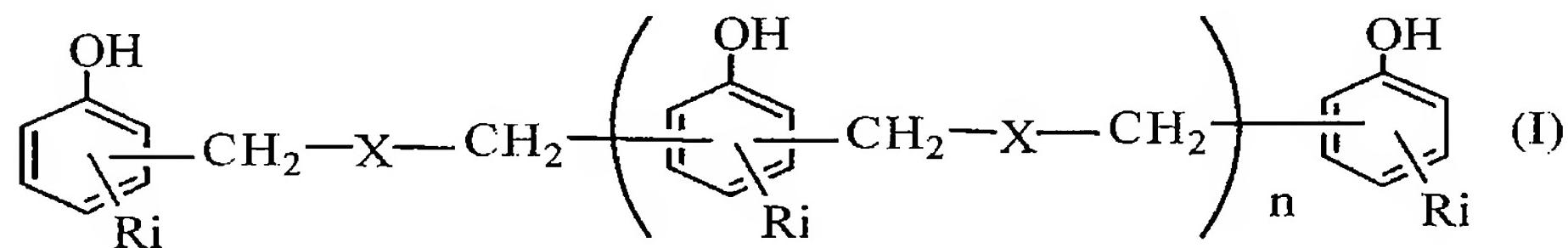
These claims will replace all prior versions of claims in the present application.

1. (Original) An epoxy resin molding material for sealing, comprising an epoxy resin, an epoxy resin curing agent, and a pitch.
2. (Original) The epoxy resin molding material for sealing according to claim 1, wherein the pitch is mesophase microspheres isolated from a mesophase pitch.
3. (Currently Amended) The epoxy resin molding material for sealing according to claim 1 or 2, wherein an electrical resistivity of the pitch is at least $1 \times 10^5 \Omega\cdot\text{cm}$.
4. (Currently Amended) The epoxy resin molding material for sealing according to any one of claims 1 through 3, wherein a carbon content of the pitch is within a range from 88 to 96% by weight.
5. (Currently Amended) The epoxy resin molding material for sealing according to any one of claims 1 through 4, further comprising one or more materials selected from the group consisting of phthalocyanine-based dyes, phthalocyanine-based pigments, aniline black, perylene black, black iron oxide, and black titanium oxide as a colorant that contains no pitch.
6. (Currently Amended) The epoxy resin molding material for sealing according to any one of claims 1 through 5, wherein a combined quantity of the colorant that contains no pitch and the pitch is within a range from 2 to 15% by weight relative to the epoxy resin.
7. (Currently Amended) The epoxy resin molding material for sealing according to any one of claims 1 through 6, wherein a quantity of the pitch relative to the combined quantity of the colorant that contains no pitch and the pitch is at least 30% by weight.
8. (Currently Amended) The epoxy resin molding material for sealing according to any one of claims 1 through 7, comprising, as the epoxy resin, one or more resins selected from

the group consisting of biphenyl type epoxy resins, bisphenol F type epoxy resins, thiodiphenol type epoxy resins, phenol-aralkyl type epoxy resins, and naphthol-aralkyl type epoxy resins.

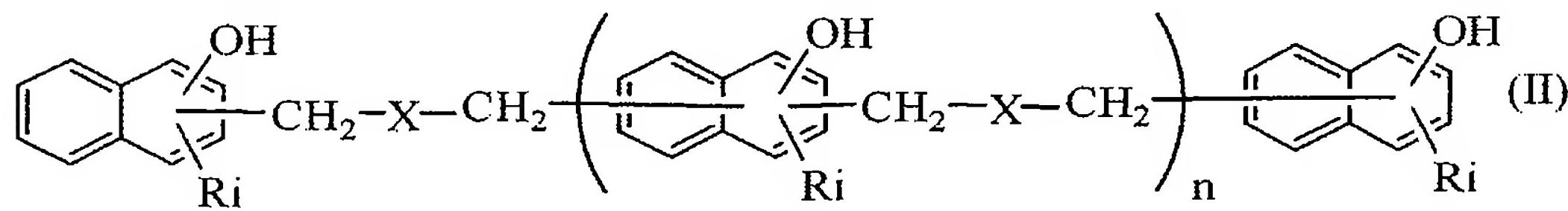
9. (Currently Amended) The epoxy resin molding material for sealing according to ~~any one of~~ claims 1 through 8, comprising, as the curing agent, one or more resins selected from the group consisting of phenol-aralkyl resins represented by a general formula (I) shown below and naphthol-aralkyl resins represented by a general formula (II) shown below:

[Formula 1]



(wherein, each R represents a hydrogen atom, or a substituted or unsubstituted monovalent hydrocarbon group of 1 to 12 carbon atoms, which may be all identical, or may be different, i represents either 0 or an integer from 1 to 3, X represents a bivalent organic group comprising an aromatic ring, and n represents either 0 or an integer from 1 to 10),

[Formula 2]

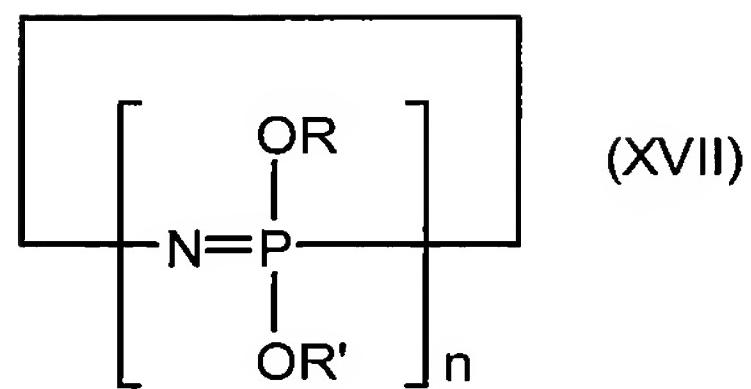


(wherein, each R represents a hydrogen atom, or a substituted or unsubstituted monovalent hydrocarbon group of 1 to 12 carbon atoms, which may be all identical, or may be different, i represents either 0 or an integer from 1 to 3, X represents a bivalent organic group comprising an aromatic ring, and n represents either 0 or an integer from 1 to 10).

10. (Currently Amended) The epoxy resin molding material for sealing according to ~~any one of~~ claims 1 through 9, further comprising a cyclic phosphazene compound.

11. (Original) The epoxy resin molding material for sealing according to claim 10, wherein the cyclic phosphazene compound comprises a compound represented by a general formula (XVII) shown below:

[Formula 3]



(XVII)

(wherein, n represents an integer from 3 to 5, and R and R' each represent an alkyl group of 1 to 4 carbon atoms or an aryl group, which may be either identical or different).

12. (Original) The epoxy resin molding material for sealing according to claim 11, wherein at least one of R and R' represents a hydroxyphenyl group, and a number of hydroxyphenyl groups is within a range from 1 to 10.
13. (Currently Amended) The epoxy resin molding material for sealing according to ~~any one of claims 10 through 12~~, comprising a cross-linked cyclic phosphazene compound.
14. (Currently Amended) An electronic component comprising an element that is sealed with the epoxy resin molding material for sealing according to ~~any one of claims 1 through 13~~.